

AT3216 Series (Preliminary)

Multilayer Chip Antenna

Features

- ❖ Monolithic SMD with small, low-profile and light-weight type.
- ❖ Wide bandwidth

Applications

- ❖ Bluetooth/Wireless LAN/Home RF
- ❖ ISM band 2.4GHz applications



Specifications

Part Number	Operating Frequency (MHz)	Peak Gain (YZ-total)	Average Gain (YZ-total)	VSWR	Impedance
AT3216 -E2R4HAA_	2400 ~ 2500	1.0 dBi typ.	-3.0 dBi typ.	4.0 max.	50 Ω

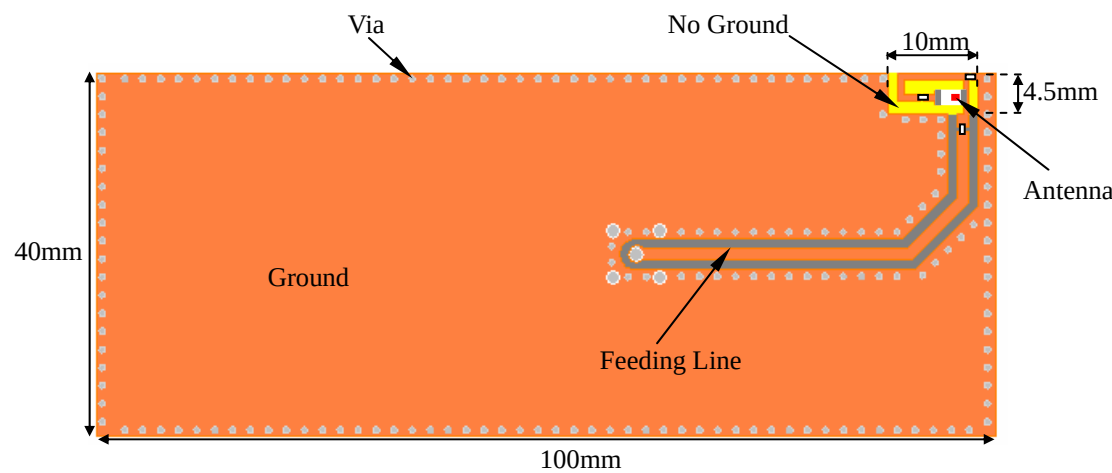
Q'ty/Reel (pcs) : 3,000pcs
 Operating Temperature Range : -40 ~ +85 °C
 Storage Temperature Range : +5 ~ +35 °C, Humidity 45~75%RH
 Storage Period : 12 months max.
 Power Capacity : 2W max.

Part Number

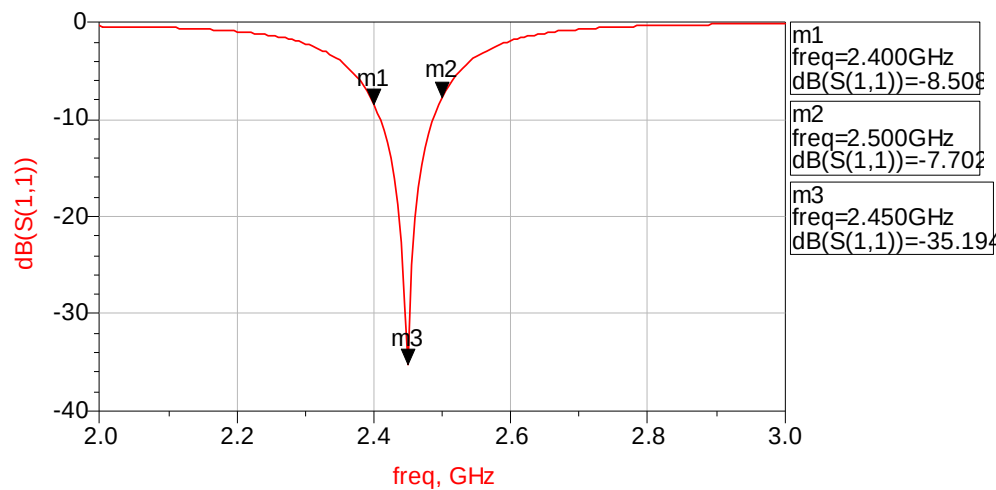
AT 3216 - E 2R4 HAA □ □
 ① ② ③ ④ ⑤ ⑥ ⑦

① Type	AT : Antenna	② Dimensions (L × W)	3.2× 1.6 mm
③ Material Code	E	④ Initial center frequency	2R4=2400MHz
⑤ Specification Code	HAA	⑥ Packaging	T: Tape & Reel B: Bulk
⑦ Soldering	=lead-containing /LF=lead-free		

❖ Test Board

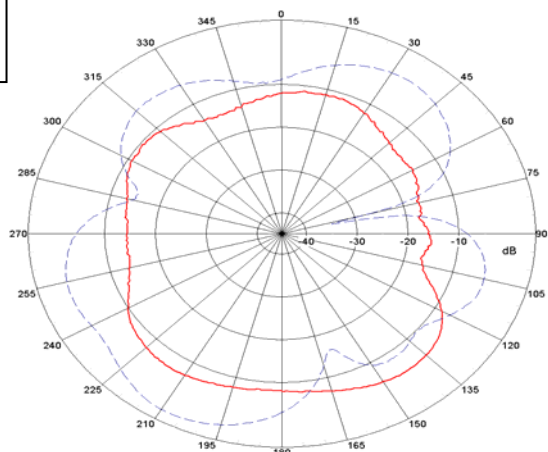
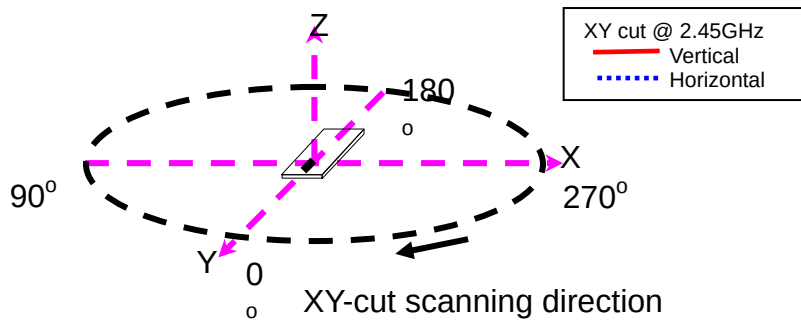


❖ Return Loss-with matching circuits

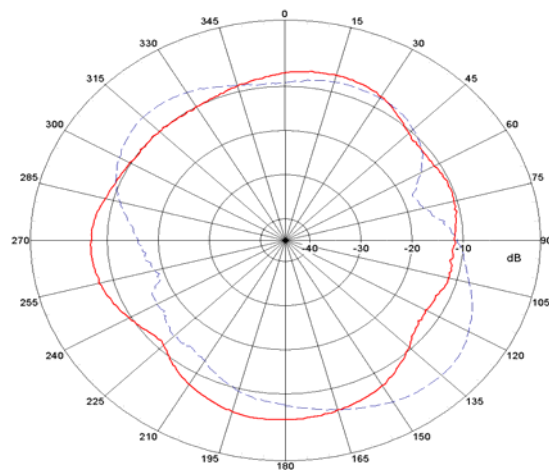
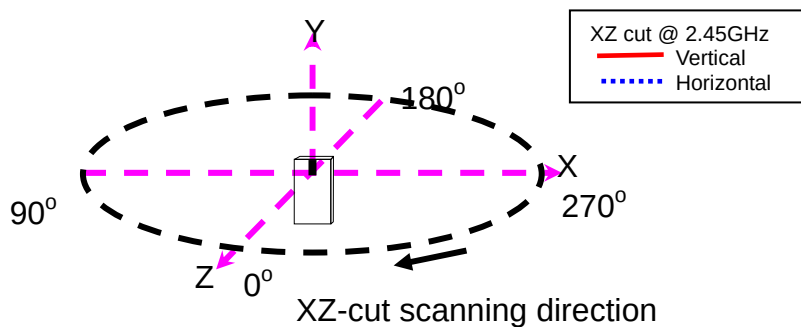


❖ Radiation Patterns

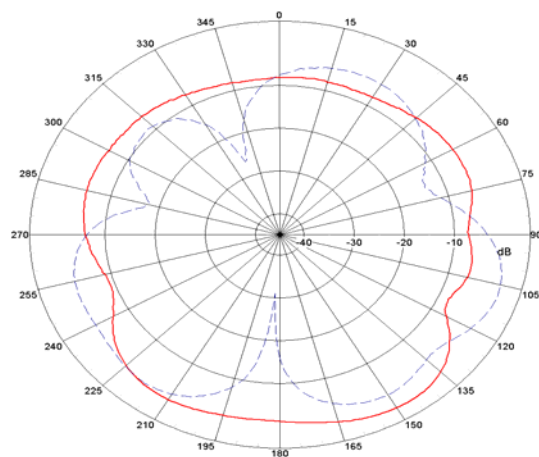
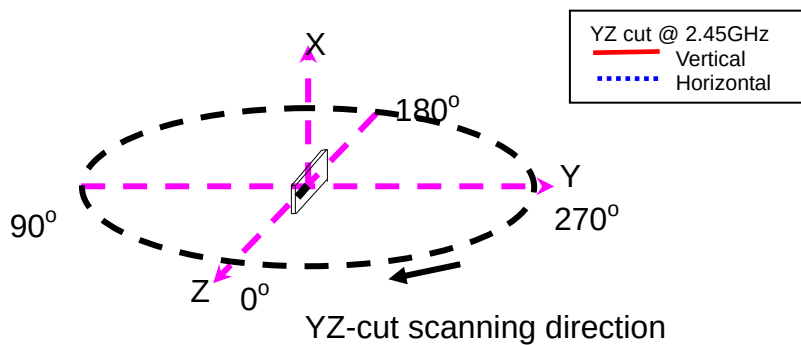
XY-V/XY-H



XZ-V/XZ-H

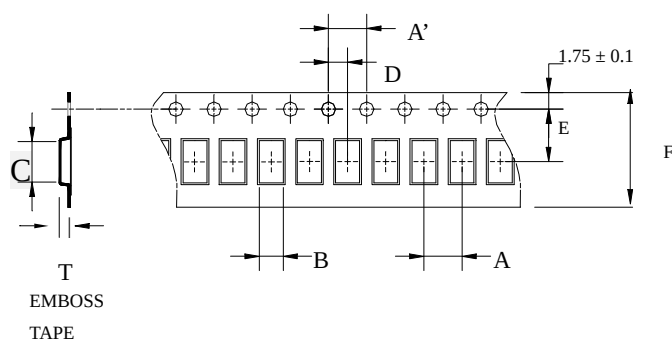


YZ-V/YZ-H



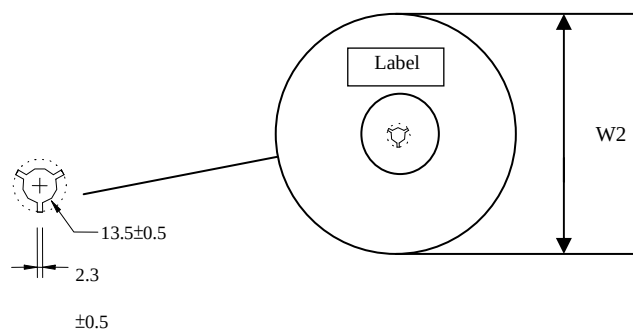
Taping Specifications

❖Tape & Reel Dimensions (Unit: mm) vs. Quantity (pcs)



Type	A	A'	B	C	D	E	F	T	Quantity/per reel	Tape material
AT3216	4.0±	4.0±	1.88±	3.5±	2.0±	3.5±	8.00±	1.27±	3,000pcs	Plastic (Embossed)
	0.1	0.05	0.1	0.1	0.05	0.05	0.1	0.1		

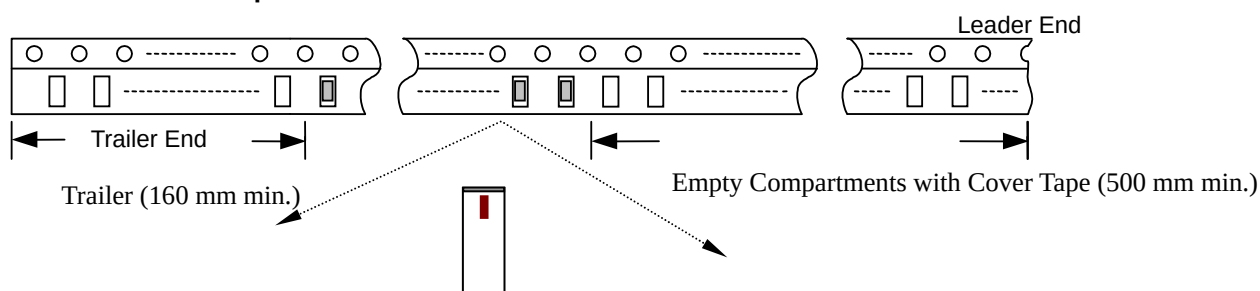
❖Reel Dimensions (Unit: mm)

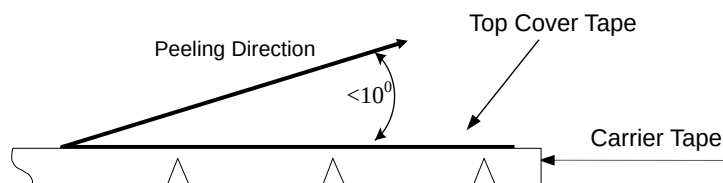


Label: Customer's Name,
ACX P/N, Q'ty, Date,
ACX Corp.

Type	W2	W3	W4	W5
AT3216	178±1	60±1	1.4±0.2	17±0.5

❖Leader and Trailer Tape



❖Peel-off Force

Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of 300 ± 10 mm/min .

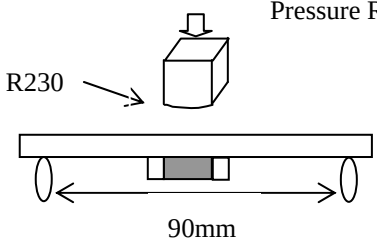
❖Storage Conditions

- (1) Temperature: $15 \sim 35^{\circ}\text{C}$, relative humidity (RH): 45~75%.
- (2) Non-corrosive environment

Notes

❖The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.

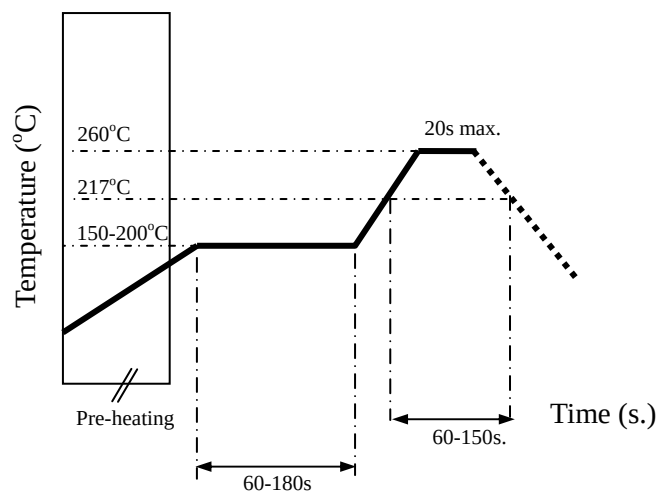
Mechanical & Environmental Characteristics

Item	Requirements	Procedure
Solderability	- No apparent damage - More than 95% of the terminal electrode shall be covered with new solder	- Preheat: $120 \pm 5^{\circ}\text{C}$ - Solder: $245 \pm 5^{\circ}\text{C}$ for 5 ± 1 sec
Soldering strength (Termination Adhesion)	1kg minimum	- Solder specimen onto test jig. - Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction
Deflection (Substrate Bending)	No apparent damage	- Solder specimen onto test jig (FR4, 0.8mm) using the recommend soldering profile. - Apply a bending force of 2mm deflection 
Heat/Humidity Resistance	- No apparent damage - Fulfill the electrical specification after test	- Temperature: $85 \pm 2^{\circ}\text{C}$ - Humidity: 90% ~ 95% RH - Duration: 1000 ± 48hrs - Recovery: 1-2hrs
Thermal shock (Temperature Cycle)	- No apparent damage - Fulfill the electrical specification after test	- One cycle/step 1 : $125 \pm 5^{\circ}\text{C}$ for 30 min step 2 : $-40 \pm 5^{\circ}\text{C}$ for 30 min - No of cycles : 100 - Recovery: 1-2 hrs
Low Temperature Resistance	- No apparent damage - Fulfill the electrical specification after test	- Temperature: $-40^{\circ} \pm 5^{\circ}\text{C}$ - Duration: 500 ± 24hrs - Recovery: 1-2hrs

Soldering Conditions

❖ Typical Soldering Profile for Lead-free Process

Reflow Soldering :



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